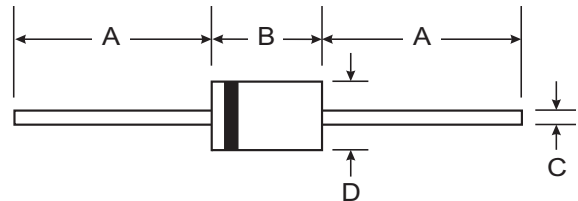


Features

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 25A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: 260°C/10 Second at Terminal
- **Lead Free Finish, RoHS Compliant (Note 3)**



Mechanical Data

- Case: DO-41
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Bright Tin. Plated Leads - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Ordering Information: See Last Page
- Marking: Type Number
- Weight: 0.3 grams (approximate)

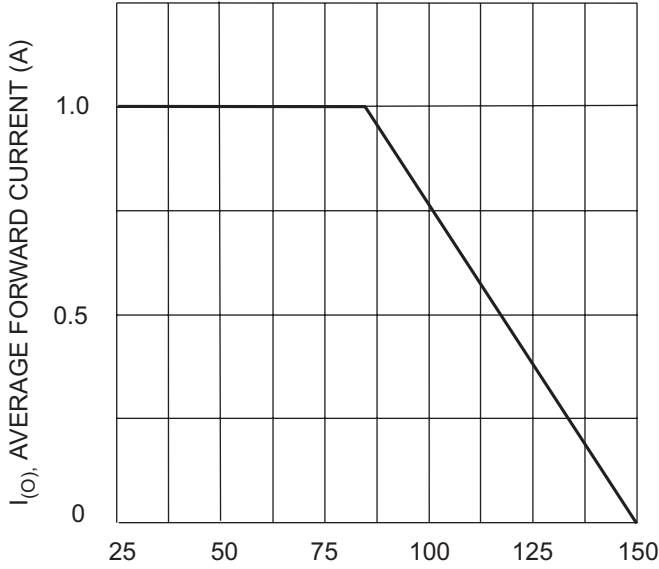
DO-41		
Dim	Min	Max
A	25.4	—
B	4.1	5.2
C	0.71	0.86
D	2.0	2.7
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

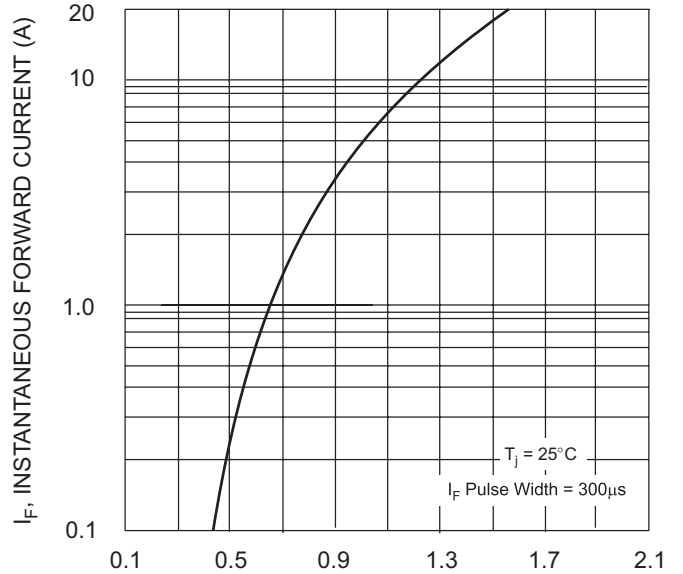
Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	SB170	SB180	SB190	SB1100	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	70	80	90	100	V
Working Peak Reverse Voltage	V _{RWM}					
DC Blocking Voltage	V _R					
RMS Reverse Voltage	V _{R(RMS)}	49	56	63	70	V
Average Rectified Output Current @ T _T = 85°C	I _o	1.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	25				A
Forward Voltage @ I _F = 1.0A @ T _A = 25°C	V _{FM}	0.80				V
Peak Reverse Current at Rated DC Blocking Voltage @ T _A = 25°C @ T _A = 100°C	I _{RM}	0.5 10				mA
Typical Junction Capacitance (Note 2)	C _j	80				pF
Typical Thermal Resistance Junction to Lead	R _{θJL}	15				K/W
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	50				K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +125				°C

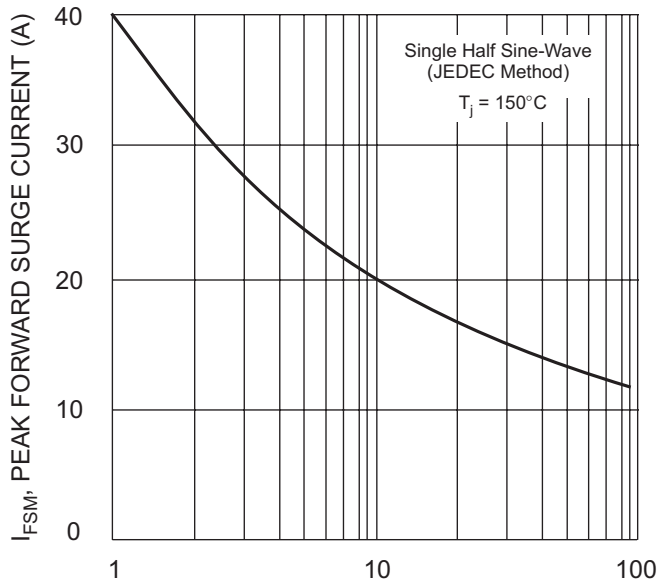
- Notes: 1. Valid provided that leads are kept at ambient temperature at a distance of 9.5mm from the case.
2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
3. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.



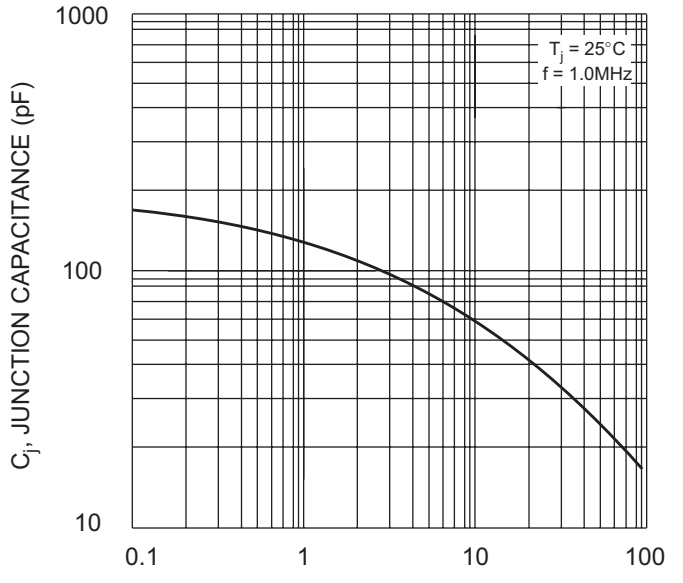
T_L , LEAD TEMPERATURE (°C)
Fig. 1 Forward Current Derating Curve



V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics



NUMBER OF CYCLES AT 60 Hz
Fig. 3 Max Non-Repetitive Peak Fwd Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Junction Capacitance

Ordering Information (Note 4)

Device	Packaging	Shipping
SB170-A	DO-41	5K/Ammo Pack
SB170-B	DO-41	1K/Bulk
SB170-T	DO-41	5K/Tape & Reel, 13-inch
SB180-A	DO-41	5K/Ammo Pack
SB180-B	DO-41	1K/Bulk
SB180-T	DO-41	5K/Tape & Reel, 13-inch
SB190-A	DO-41	5K/Ammo Pack
SB190-B	DO-41	1K/Bulk
SB190-T	DO-41	5K/Tape & Reel, 13-inch
SB1100-A	DO-41	5K/Ammo Pack
SB1100-B	DO-41	1K/Bulk
SB1100-T	DO-41	5K/Tape & Reel, 13-inch

Notes: 4. For packaging details, visit our website at <http://www.diodes.com/datasheets/ap02008.pdf>